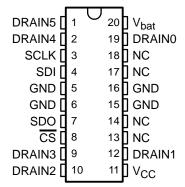
- Serial Control With Diagnostics
- Six Power DMOS Transistor Outputs of 350-mA Continuous Current
- Internal 60-V Inductive Load Clamp
- Independent ON-State Shorted-Load/Short-to-Battery Fault Detection on All Drain Terminals
- Independent OFF-State Open-Load Fault Sense on All Drain Terminals
- Transition of Drain Outputs to Low Duty Cycle Pulsed-Width-Modulation (PWM) Mode for Over-Current Condition
- Over-Battery-Voltage-Lockout Protection
- Over-Temperature Sense With Serial Interface Fault Status
- Fault Diagnostics Returned Through Serial Output Terminal
- Internal Power-On Reset of Registers
- CMOS Compatible Inputs With Hysteresis

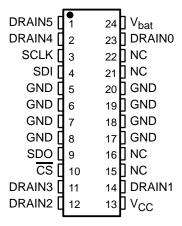
description

The TPIC2603 is a monolithic low-side driver which provides serial interface and diagnostics to control six on-board power DMOS switches. Each channel has independent OFF-state open-load sense, ON-state shorted-load/short-to-battery protection, over-battery-voltage-lockout protection, and over-temperature sense with fault status reported through the serial interface. The device also provides inductive voltage transient protection for each drain output. The TPIC2603 drives inductive and resistive loads such as relays, valves, and lamps.

NE PACKAGE (TOP VIEW)



DW PACKAGE (TOP VIEW)



NC - No internal connection

Serial data input (SDI) is transferred through the serial register when \overline{CS} is low on low-to-high transitions of the serial clock (SCLK). Each string of data must consist of 8 or 16 bits of data. A logic high input data bit turns the respective output channel ON and a logic low data bit turns it OFF. \overline{CS} must be transited high after all of the serial data has been clocked into the device. A low-to-high transition of \overline{CS} transfers the last six bits of serial data to the output buffer, places the serial data out (SDO) terminal in a high-impedance state, and re-enables the fault register. Fault data for the device is sent out the SDO terminal. The first bit of the shift register is exclusively ORed with the fault registers. When a fault exists, the SDI data is inverted as it is transferred out of SDO. Fault data consists of fault flags for over-temperature (bit 6) and shorted/open-load (bits 0-5) for each of the six output channels. Fault register bits are set or cleared asynchronously, when \overline{CS} is high to reflect the current state of the hardware. The fault must be present when \overline{CS} is transited from high to low to be captured and reported in the serial fault data. New faults cannot be captured in the serial register when \overline{CS} is low.



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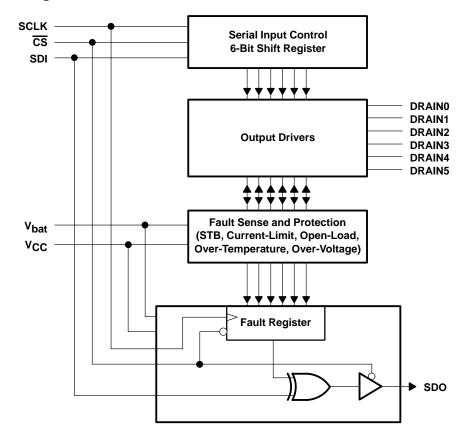
description (continued)

When an over-current or shorted-load fault occurs, the channel transits into a low duty cycle pulse-width-modulated (PWM) signal as long as the fault is present. More detail on fault detection operation is presented in the device operation section of this data sheet.

The TPIC2603 provides pulldown resistors on all active-high inputs except SCLK. A pullup resistor is used on $\overline{\text{CS}}$.

The TPIC2603 is characterized for operation over the operating case temperature of -40°C to 125°C.

functional block diagram





Terminal Functions

TERMINAL		1/0	DECODIDATION				
NAME	NO.†	1/0	DESCRIPTION				
CS	8 (10)	_	Chip select. The $\overline{\text{CS}}$ is an active-low input used to select the serial interface of the device. The device accepts serial input data and transmits fault data when $\overline{\text{CS}}$ is held low. An internal pullup resistor is provided on the $\overline{\text{CS}}$ input.				
DRAINO DRAIN1 DRAIN2 DRAIN3 DRAIN4 DRAIN5	19 (23) 12 (14) 10 (12) 9 (11) 2 (2) 1 (1)	0	FET drain outputs. The DRAIN terminals are low-side switches for inductive and resistive loads. Each output provides an internal drain-gate clamp to snub inductive transients.				
GND	5, 6, 15, 16 (5, 6, 7, 8, 17, 18, 19, 20)	0	Ground. These terminals provide ground return paths for the device.				
SCLK	3 (3)	I	Serial clock. The SCLK clocks the shift register. Serial data is transferred into the SDI port and serial fault data is transferred out of the SDO port of the device on the rising edges of SCLK.				
SDI	4 (4)	I	Serial data input. The device receives serial data from the control device using the SDI. Serial input data can be configured in 8-bit or 16-bit data words. Refer to Figures 2 and 4 for input protocol. An internal pulldown resistor is provided on the SDI input.				
SDO	7 (9)	0	Serial data output. This 3-state output transfers fault data to the control device after the device has been selected by the $\overline{\text{CS}}$ terminal.				
V _{bat}	20 (24)	I	Battery voltage. The V _{bat} terminal monitors the battery voltage to detect over-voltage conditions.				
VCC	11 (13)	Ī	Supply voltage. The V _{CC} terminal receives a 5-V supply for internal logic.				

[†] Terminal numbers listed in parenthesis are for the 24-pin DW package.

absolute maximum ratings over the recommended operating case temperature range (unless otherwise noted)‡

Logic supply voltage range, V _{CC} (see Note 1)	0.3 V to 7 V
Battery supply voltage range, V _{bat}	
Logic input voltage range, V _I	0.3 V to 7 V
Power DMOS drain-to-source voltage, V _{DS} (see Note 2)	68 V
Continuous drain current, each output, all outputs on, ID, TC = 25°C	350 mA
Pulsed drain current, single output, I _{DM} , T _C = 25°C (see Note 3)	2.25 A
Single-pusle avalanche energy, E _{AS} (see Figure 11)	
Continuous total power dissipation	See Dissipation Rating Table
Avalanche current, I _{AS} (see Note 4)	1 A
Operating virtual junction temperature range, T _J	
Storage temperature range, T _{stq}	–55°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to GND.
 - 2. Each power DMOS source is internally connected to GND.
 - 3. Pulse duration \leq 100 μ s and duty cycle \leq 2%.
 - 4. DRAIN supply voltage = 13 V, starting junction temperature (TJS) = 25°C, L = 150 mH, IAS = 1 A (see Figure 11).



DISSIPATION RATING TABLE

PACKAGE	$T_C \le 25^{\circ}C$ POWER RATING	DERATING FACTOR ABOVE T _C = 25°C	T _C = 125°C POWER RATING		
DW	1750 mW	14 mW/°C	350 mW		
NE	2500 mW	20 mW/°C	500 mW		

recommended operating conditions

	MIN	NOM	MAX	UNIT
Logic supply voltage, V _{CC}	4.5	5	5.5	V
Battery supply voltage, V _{bat}	5.5	12	25	V
High-level input voltage, V _{IH}	0.7 V _{CC}		Vcc	V
Low-level input voltage, V _{IL}	0		0.3 V _{CC}	V
Operating case temperature, T _C	-40		125	°C

electrical characteristics, $T_C = -40^{\circ}C$ to 125°C (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	MIN	TYP	MAX	UNIT
V _{bat}	Battery supply voltage	Normal operation		5.5		25	V
I _{hat} Battery supply current		V _{CC} = 5 V			5	mA	
^I bat	battery supply current	VCC = 0				50	μΑ
Vcc	Logic supply voltage			4.5		5.5	V
ICC	Logic supply current	All outputs off,	$V_{\text{bat}} = 5.5 \text{ V}$			5	mA
V _(turn-on)	VCC turn-on voltage	$V_{\text{bat}} = 5.5 \text{ V},$	Check output functionality			4.5	V
V _(ov)	Over-battery voltage shutdown	Gate disabled		30		38	V
V _{hys(ov)}	Over-battery voltage reset hysteresis			0.4		2	V
		V _{bat} = 13 V	L 0.05 A T 0500		0.7	1	Ω
1_	Drain-to-source on-state resistance	V _{bat} = 5.5 V	$I_{O} = 0.35 \text{ A}, T_{C} = 25^{\circ}\text{C}$		1.7	2.3	
^r DS(on)		V _{bat} = 13 V	L- 0.25 A T- 4.250C		1.2	1.7	
		V _{bat} = 5.5 V	$I_{O} = 0.35 \text{ A}, T_{C} = 125^{\circ}\text{C}$		2.7	3.8	
IL	On-state current limit			0.8	2	5	Α
I _{L(sense)}	Over-current sense			0.8	1.5	3	Α
lН	Input pullup current	$GND < V_I < 0.7 \; V_{CC},$	CS input only	-5	-10	-50	μΑ
I _{IL}	Input pulldown current	0.3 V _{CC} < V _I < V _{CC} ,	All other inputs	2.5	10	25	μΑ
I _{D(off)}	Off-state drain current	$V_{load} = V_{bat} = 14.5 V$		20	40	80	μΑ
IO(sleep)	Sleep-state output current	V _{bat} < 0.5 V,	$V_{CC} < 0.5 \text{ V}$, Load = 14 V			50	μΑ
Vон	High-level serial output voltage	I _O = 1 mA		0.8 V _{CC}			V
VOL	Low-level serial output voltage	I _O = 1 mA			0.2	0.4	V
loz	High impedance state output current	$V_{CC} = 5.5 \text{ V to 0 V},$	SDO output	-10	1	10	μΑ
V _{(BR)DSX}	Drain-to-source breakdown voltage	dc < 1%,	$t_W = 100 \ \mu s$, $I_O = 20 \ mA$	52	58	68	V
T _{j(sense)}	Thermal flag			150	170	185	°C
T _{j(hys)}	Thermal flag hysteresis			5	10	15	°C
V _(open)	Open-load detection voltage			0.3 V _{CC}		0.7 V _{CC}	V



switching characteristics, V_{CC} = 5 V, T_{C} = 25°C

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _W	Clock cycle period pulse duration, SCLK	See Figure 1		250	555	ns
twH(SCLK)	Pulse duration, SCLK high	See Figure 1		100	248	ns
twL(SCLK)	Pulse duration, SCLK low	See Figure 1		100	248	ns
^t pd1	Propagation delay from falling edge of $\overline{\text{CS}}$ to SDO valid	CS = 0.8 V to SDO low impedance (see Figure 1)		150	300	ns
t _{pd2}	Propagation delay from rising edge of CS to SDO 3-state	CS = 2 V to SDO 3-state		150	200	ns
t _{pd3}	Propagation delay from SCLK to SDO valid	CS < 0.8 V		80	172	ns
tr(SDO)	Rise time of SDO	C _{load} = 200 pF		30	50	ns
tf(SDO)	Fall time of SDO	C _{load} = 200 pF		30	50	ns
t(stb)	Short-to-battery/shorted-load/open-load deglitch time	See Figures 5 and 6	25	70	100	μs
^t d(on)	Turn-on delay time, rising edge of CS to drain		0.4	5	10	
^t d(off)	Turn-off delay time, rising edge of CS to drain	$V_{\text{bat}} = 14 \text{ V},$ $R_{\text{load}} = 30 \Omega$	0.4	5	15	
^t r(drain)	Rise time of drain terminal	$R_{load} = 30 \Omega$	0.4	5	10	μs
^t f(drain)	Fall time of drain terminal		0.4	5	10	
f(SCLK)	Serial clock frequency		1.8	4		MHz
tcyc(ref)	Short-to-battery sense cycle time	See Figure 5	1.6	4	6.4	ms
tw(sense)	Short-to-battery sense pulse duration	See Figure 5	25	70	100	μs
t _{su1}	Setup to/from the fall edge of $\overline{\text{CS}}$ to the rising edge of SCLK	See Figure 1		150	200	ns
t _{su(SDI)}	Setup time, SDI to SCLK	See Figure 1		25	55	ns
th(SDI)	Hold time, SDI after SCLK	See Figure 1		10	55	ns

thermal resistance

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	All outputs with equal power		50	°C
$R_{\theta JC}$	Junction-to-case thermal resistance	All outputs with equal power		10	°C

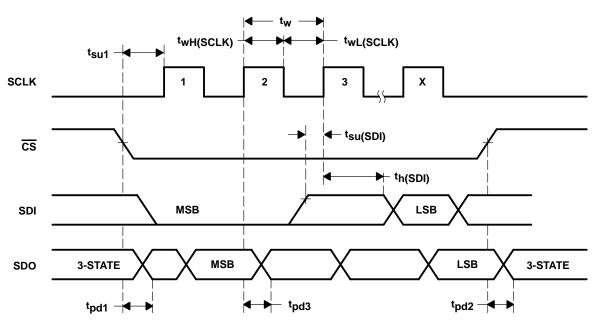


Figure 1. Switching Characteristics

serial interface

Control information is transferred into the TPIC2603 through the serial interface. The serial interface consists of a serial clock (SCLK), chip select (\overline{CS}) , serial data input (SDI), and serial data output (SDO). Serial data is shifted, most significant bit (MSB) first, into the SDI shift register on the rising edge of the first SCLK after \overline{CS} has transited from high to low. The controller must shift either eight bits or sixteen bits of data into the device with the last six bits of input data containing control information for the output drivers. Data bits preceeding the output control information should be set to 0. A low-to-high transition on \overline{CS} latches the contents of the last six bits of the serial shift register into the output buffer. A low input to SDI turns the corresponding parallel output OFF and a high input will turn the output ON (see Figure 2).

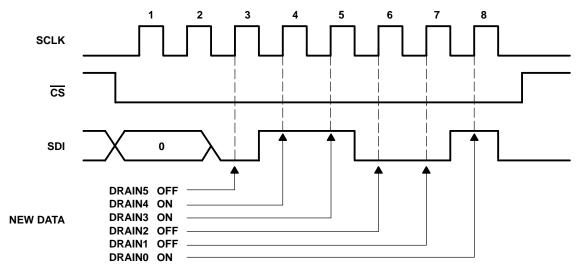
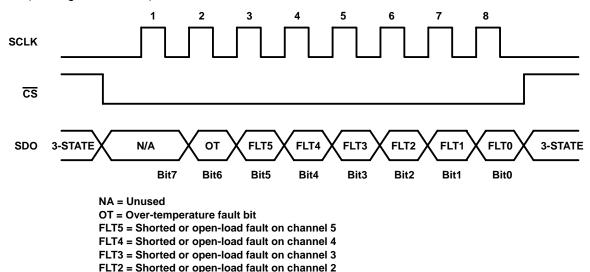


Figure 2. Serial Input Control



serial interface (continued)

Fault isolation data for each channel and global over-temperature status is transferred to the control device using the serial interface. Fault status for the TPIC2603 is captured as \overline{CS} transits low. The fault interface monitors the SDI terminal and exclusively ORs the respective input control bit with the corresponding fault information bit stored in the fault register. Each exclusive ORed fault bit is transferred out the SDO terminal on the rising edge of the SCLK. Serial data can be transferred in 8-bit or 16-bit words as illustrated in Figure 4, with fault data appearing in the first 8-bits of serial output data. The \overline{CS} must be transited high after the serial transfer has completely latched the new control data into the output control buffer and re-enable fault reporting on the device (see Figures 3 and 4).



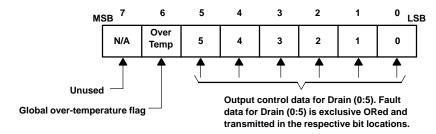
NOTE A: MSB is the first bit transferred.

Figure 3. Serial Output Control

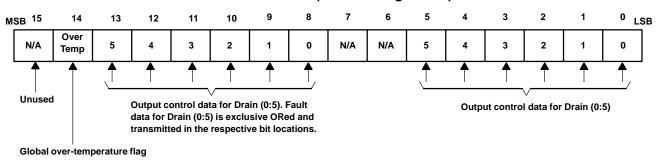
FLT1 = Shorted or open-load fault on channel 1 FLT0 = Shorted or open-load fault on channel 0

serial interface (continued)

Serial I/O Protocol (8-Bit Configuration)



Serial I/O Protocol (16-Bit Configuration)



NOTE A: MSB is the first bit transferred.

Figure 4. Serial Data Fault Protocol



fault sense/protection circuitry

over-current/short-to-battery sensing and protection

The internal fault protection circuitry of the TPIC2603 monitors the drain current for each channel. Each channel offers two levels of protection from over-current conditions. The first level is a current-limit protection which through the internal FET prevents the switching current from exceeding the on-state current limit. The second level of protection transits the output to a low duty cycle PWM mode when the current exceeds the over-current sense threshold. The PWM mode protection is enabled approximately 70 μ s after the output has been turned on. The output remains in the PWM mode until the shorted-load condition has been corrected and then automatically returns to normal operation. Figure 5 illustrates device operation under an over-current or shorted-load condition.

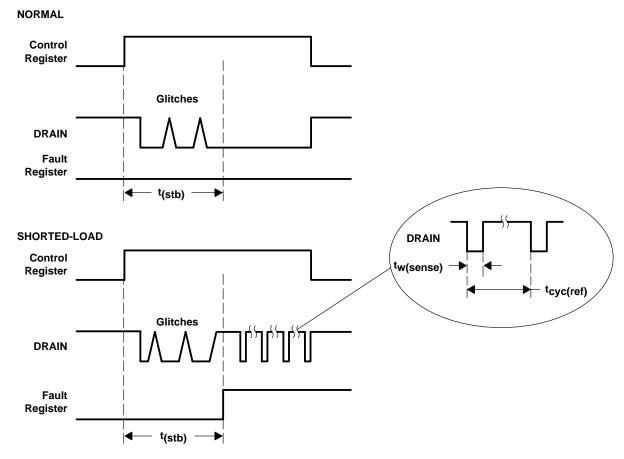


Figure 5. Shorted-Load Condition

open-load/short-to-ground sensing

The TPIC2603 checks for open-load and short-to-ground conditions when the output is turned OFF. When the output turns OFF, a 40- μ A current source switches onto the drain. Under normal conditions, the load provides adequate current to overcome the current source and the drain voltage remains above the open-load detection threshold. When the output is open, then the current source pulls the drain low and an open-load condition is flagged. The open-load test is enabled approximately $70~\mu s$ after the output turns OFF to allow the drain to stabilize. Figure 6 illustrates device operation under open-load conditions.

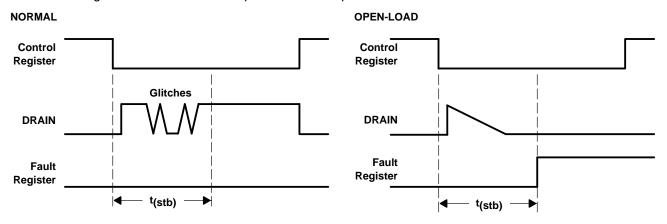


Figure 6. Open-Load Condition

over-voltage sensing and protection

The TPIC2603 monitors the V_{bat} input terminal to protect the device and load from over-battery voltage conditions. The device disables all of the drain outputs when V_{bat} goes above 35 V. An over-battery voltage hysteresis is provided to prevent the outputs from transiting ON and OFF erratically near the over-voltage threshold. The device automatically returns to normal operation after the over-voltage condition has been corrected. Figure 7 illustrates device operation under an over-battery voltage condition.

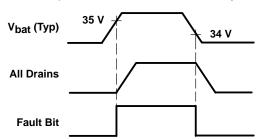


Figure 7. Over-Battery Voltage Condition



over-temperature sensing

The TPIC2603 monitors the junction temperature of the die to detect over-temperature conditions which may damage the device. When the junction temperature goes above approximately 170°C, the fault logic sets the global over-temperature fault bit. An over-temperature fault is reported using the serial interface on bit 6 (for 8-bit configuration) or bit 14 (for 16-bit configuration). The global over-temperature fault output in the serial data is exclusively ORed with the second bit (bit 6 for 8-bit configuration or bit 14 for 16-bit configuration) of data input to the SDI terminal. Bit 6 or bit 14 of the input data should be set low. Over-temperature faults are for informational purposes only and do not affect the state of the drains. Figure 8 illustrates device operation under over-temperature conditions.

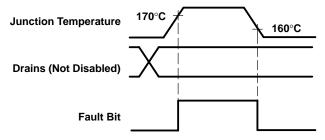


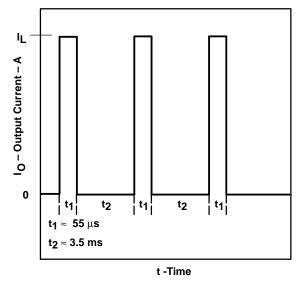
Figure 8. Over-Temperature Sense

PARAMETER MEASUREMENT INFORMATION

TIME FOR INCREASING LOAD RESISTANCE TC = 25°C Region 1 Region 2 Region 3 t - Time

OUTPUT CURRENT

REGION 1 CURRENT WAVEFORM



First output current pulses after turn-on in chopping mode with resistive load.

- NOTES: A. Region 1 Analog current limit holds the maximum current while the device runs in chop mode.
 - B. Region 2 Analog current limit is removed but device continues in chop mode.
 - C. Region 3 Current is below chop mode sense; therefore, it is in normal operation. Variable load is resistance over time.

Figure 9. Chopping-Mode Characteristics



PARAMETER MEASUREMENT INFORMATION

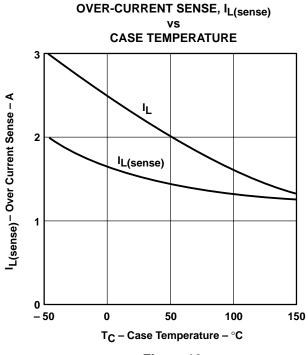
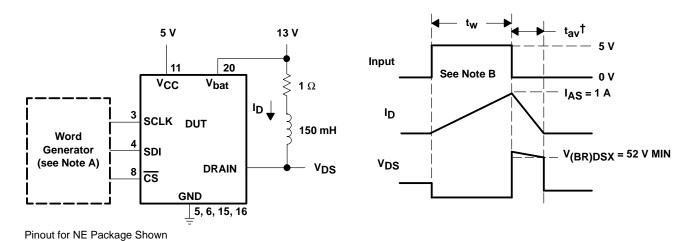


Figure 10



SINGLE-PULSE AVALANCHE ENERGY TEST CIRCUIT

VOLTAGE AND CURRENT WAVEFORMS

† Non-JEDEC symbol for avalanche time.

NOTES: A. The word generator has the following characteristics: $t_r \le 10$ ns, $t_f \le 10$ ns, $z_0 = 50 \Omega$.

B. Input pulse duration, t_W , is increased until peak current $I_{AS} = 1$ A. Energy test level is defined as $E_{AS} = (I_{AS} \times V_{(BR)DSX} \times t_{av})/2 = 100 \text{ mJ}.$

Figure 11. Single-Pulse Avalanche Energy Test Circuit and Waveforms

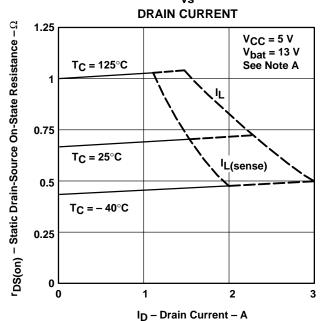


TYPICAL CHARACTERISTICS

MAXIMUM CONTINUOUS DRAIN CURRENT OF EACH OUTPUT NUMBER OF OUTPUTS CONDUCTING **SIMULTANEOUSLY** 1.6 $V_{CC} = 5 V$ I_D – Maximum Continuous Drain Current 1.4 V_{bat} = 13 V 1.2 $T_C = 25^{\circ}C$ of Each Output - A 1 0.8 T_C = 100°C 0.6 0.4 T_C = 125°C 0.2 O N - Number of Outputs Conducting Simultaneously

Figure 12

STATIC DRAIN-SOURCE ON-STATE RESISTANCE vs



NOTE A: Technique should limit $T_J - T_C$ to 10°C maximum.

Figure 14

MAXIMUM PEAK DRAIN CURRENT OF EACH OUTPUT

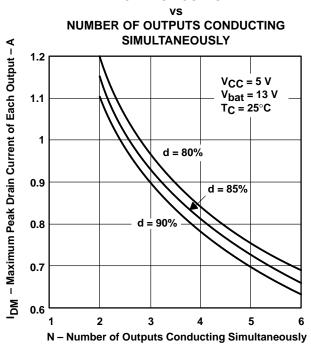
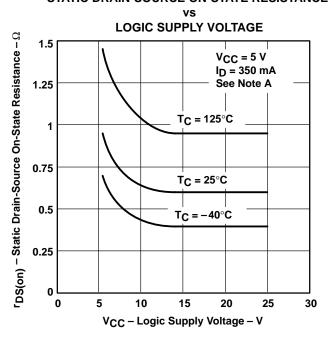


Figure 13

STATIC DRAIN-SOURCE ON-STATE RESISTANCE

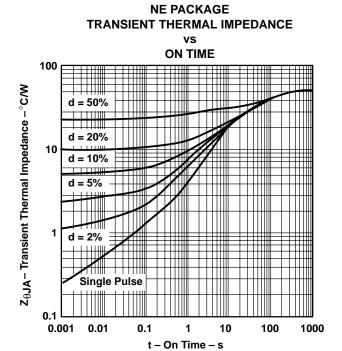


NOTE A: Technique should limit $T_J - T_C$ to 10°C maximum.

Figure 15



THERMAL INFORMATION



The single-pulse curve represents measured data. The curves for various pulse durations are based on the following equation:

$$\begin{split} Z_{\theta JA} &= \left| \begin{array}{c} \frac{t_w}{t_c} \right| R_{\theta JA} + \left| \begin{array}{c} 1 - \frac{t_w}{t_c} \right| Z_{\theta}(t_w + t_c) \\ \\ &+ Z_{\theta}(t_w) - Z_{\theta}(t_c) \end{split}$$

Where:

 $\mathbf{Z}_{\theta}(\mathbf{t_{W}}) = \underset{\text{for } t = \ t_{W}}{\text{the single-pulse thermal impedance}}$

 $Z_{\theta}(t_{c}) \ = \ the \ single-pulse \ thermal \ impedance \\ for \ t = \ t_{C} \ seconds$

 $Z_{\theta}(t_W + t_C) = \text{the single-pulse thermal impedance}$ for $t = t_W + t_C \text{ seconds}$

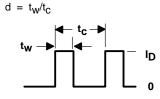


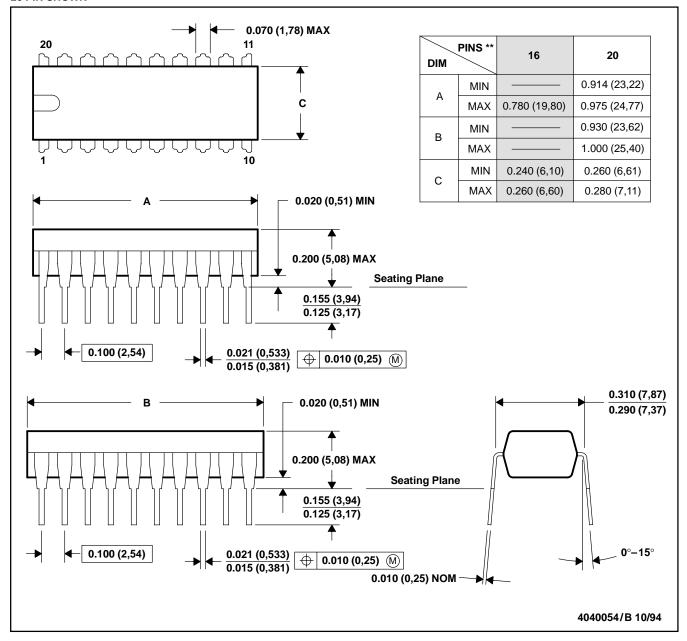
Figure 16

MECHANICAL DATA

NE (R-PDIP-T**)

20 PIN SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

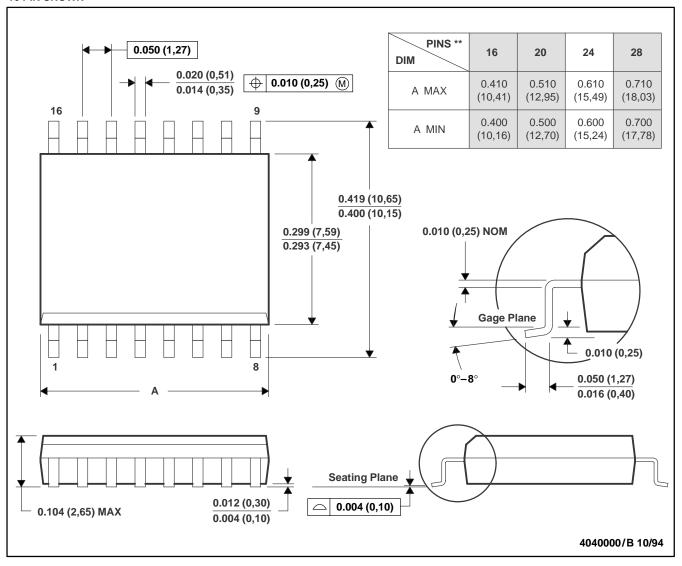
C. Falls within JEDEC MS-001 (16 pin only)

MECHANICAL DATA

DW (R-PDSO-G**)

16 PIN SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013



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